ON Semiconductor

INITIAL PRODUCT/PROCESS CHANGE NOTIFICATION #16661

Generic Copy

Issue Date: 07-Jun-2011

TITLE: Conversion to Matte Tin for Leadframe Packages due to SnPb Plating EOL in ASE CL

PROPOSED FIRST SHIP DATE: 01-Nov-2011

AFFECTED CHANGE CATEGORY(S): Assembly – Plating Material

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact your local ON Semiconductor Sales Office or Sarah Sanico <ffxxxh@onsemi.com >

NOTIFICATION TYPE:

Initial Product/Process Change Notification (IPCN)

First change notification sent to customers. IPCNs are issued at least 120 days prior to the implementation of the change. An IPCN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.

The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN).

This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change.

DESCRIPTION AND PURPOSE:

This is an ASE business decision due to the industry trend to conversion to Pb-free lead finish. The demand for tin-lead (SnPb) plating from customers is decreasing and has resulted in low utility and inefficiency of the SnPb plating line.

This change to matte tin & standardizing to Hitachi EN4900 with G700 molding compound the affected devices are RoHS compliant and Halide Free.

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QUALIFICATION PLAN:

Estimated Date for Qualification Completion: July 30, 2011
Samples should be available after completion of Qualification.

Test #	Test	Reference	Test Conditions	Comments
A1	Moisture Preconditioning (PC)	J-STD-020 & JESD22-A1-13	Moisture Soak (MSL=2) Solder Reflow (3x@260 deg C)	Surface mount devices only. Preconditioning before tests A0(SAT), A3 (AC/THU), A4 (TC)
A0	Delamination Check (SAT)	J-STD-020	Acoustic Microscopy	Samples preconditioned per test A1 (PC)
A4	Temperature Cycling (TC)	JESD22-A104	-65 deg to 150 deg C cycles	Samples preconditioned per test A1 (PC). Test conditions are dependent on environment.
	Wire bond Pull Strength (WBP)	MIL-STD883 Method 2011	Cond. C or D. Minimum pull strength after temperature cycle = 3 grams	DPA after TC
	External Visual	Mil –Std-883 3D method 2009		Perform all parts

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List of affected General Parts:

PART
0HLAA-002-XTP
0HLAA-004-XTP
0WCGA-001-XTP
11825-808-XTD
11825-808-XTP
11825-830-XTP

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List of affected Customer Specific Parts:

PART
0CTSA-003-XTD
0CTSA-003-XTP
0DDRA-002-XTD
0HLAA-001-XTD
0HLAA-001-XTP
0INDA-003-XTP
0JACB-001-XTP
0MTHA-001-XTD
0MTHA-001-XTP
0PNPA-001-XTP
0REMQ-002-XTP
0REMQ-003-XTP
0RLSA-003-XTP
0TOGB-002-XTP
0VBCA-006-XTP
0WCGA-001-XTD
0WFCA-002-XTP
0WOCA-001-XTP
11138-802-XTD
11138-802-XTP
12069-001-XTD
12069-001-XTP